

CERTIFICATE OF MAILING

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Gwyn J. Cantrell

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent application of:

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Shunpei YAMAZAKI et al.

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Serial No.: 09/437,135

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Group Art Unit: 2813

Filed: November 10, 1999

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Examiner: E. Kielin

For: SEMICONDUCTOR DEVICE AND)
METHOD FOR FORMING THE SAME)

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Responsive to the Office Action dated **September 17, 2001**, the following amendments and remarks are submitted in connection with the above-identified application.

IN THE CLAIMS:

Please amend claims 1, 6, 11, 30, and 34 as follows. Attached hereto is a marked up copy of the claims in their amended form.

1. (Thrice Amended) A method for manufacturing a semiconductor device comprising the steps of:

forming a semiconductor film comprising amorphous silicon over a substrate;

crystallizing said semiconductor film by irradiating a laser light;

patterning the crystallized semiconductor film to form first and second semiconductor islands;

forming an insulating film on each of said first and second semiconductor islands by a vapor phase deposition;